

规格书编号

SPEC NO:

# 产品规格书

# SPECIFICATION

CUSTOMER 客户: \_\_\_\_\_

PRODUCT 产品: \_\_\_\_\_ SAW FILTER

MODEL NO 型号: \_\_\_\_\_ HDF696A3-F11

PREPARED 编制: \_\_\_\_\_ CHECKED 审核: \_\_\_\_\_

APPROVED 批准: \_\_\_\_\_ D A T E 日期: \_\_\_\_\_ 2012-9-27

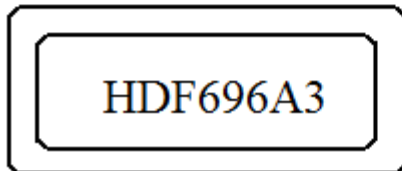
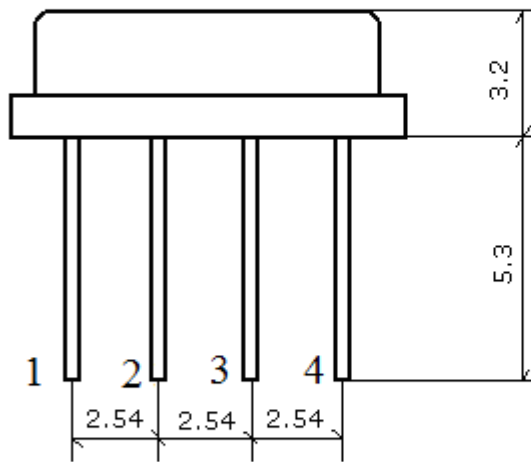
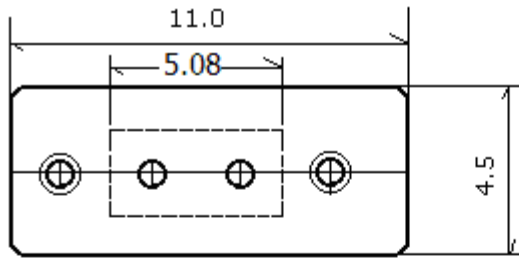
客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

无锡市好达电子有限公司  
Shoulder Electronics Limited

## 更改历史记录 History Record

更改日期 Date	规格书编号 Spec. No.	产品型号 Part No.	客户产品型号 Customer No.	更改内容描述 Modify Content	备注 Remark

### 1. Package Dimension



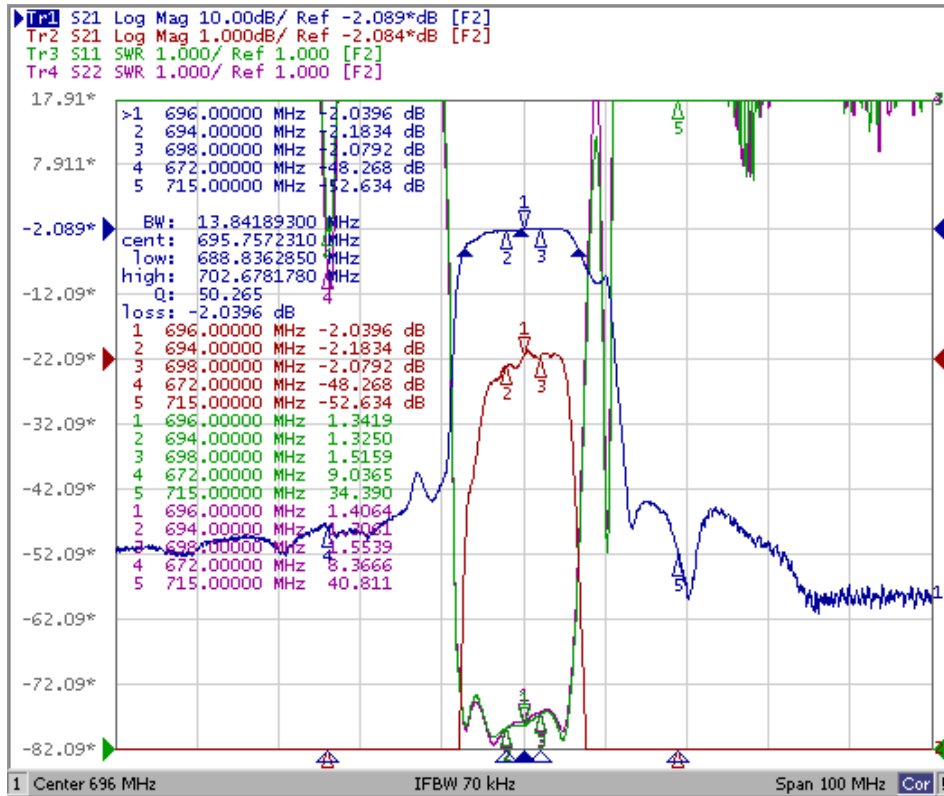
Pin configuration

- 1. Input
- 4. Output
- 2,3 Ground

### 2. Maximum Rating

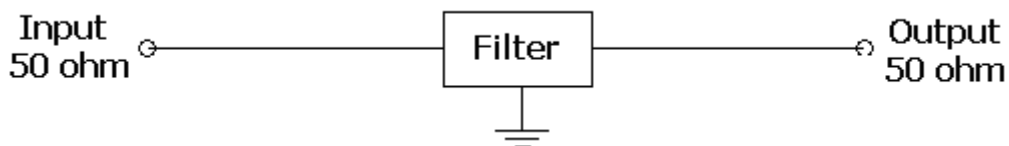
Operation Temperature Range	-40°C to +85°C
Storage Temperature Range	-40°C to +85°C
Maximum DC Voltage	10 V
Maximum Input Power	10 dBm

**3. Performance**



	Unit	Minimum	Typical	Maximum
Center Frequency Fc	MHz	-	696	-
Insertion Loss (696 ± 2 MHz)	dB		2.5	4.0
Amplitude Ripple(696 ± 2 MHz)	dB		0.5	1.0
Absolute Group Delay at Fc	nsec		100	
Group Delay Variation(696 ± 2 MHz)	nsec		50	
VSWR(696 ± 2 MHz)			1.5	2.0
Absolute Attenuation				
DC~ 672 MHz	dB	40	50	-
715 ~ 1100 MHz		40	50	
1100 ~ 1500 MHz		35	40	
1500 ~ 2500 MHz		30	38	
Input/Output Impedance	Ohms		50	

**Test Circuit**



## **4. ENVIRONMENTAL CHARACTERISTICS**

### **4.1 High temperature exposure**

Subject the device to +85°C for 16 hours. Then release the filter into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2-2.

### **4.2 Low temperature exposure**

Subject the device to -40°C for 16 hours. Then release the device into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2-2.

### **4.3 Temperature cycling**

Subject the device to a low temperature of -40°C for 30 minutes. Following by a high temperature of +85°C for 30 Minutes. Then release the device into the room conditions for 24 hours prior to the measurement. It shall meet the specifications in 2-2.

### **4.4 Resistance to solder heat**

Dip the device terminals no closer than 1.5mm into the solder bath at 260°C  $\pm$ 10°C for 10 $\pm$ 1 sec. Then release the device into the room conditions for 4 hours. The device shall meet the specifications in 2-2.

### **4.5 Solderability**

Subject the device terminals into the solder bath at 245°C  $\pm$ 5°C for 5s, More than 95% area of the terminals must be covered with new solder. It shall meet the specifications in 2-2.

### **4.6 Mechanical shock**

Drop the device randomly onto the concrete floor from the height of 1m 3 times. the device shall fulfill the specifications in 2-2.

### **4.7 Vibration**

Subject the device to the vibration for 1 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The device shall fulfill the specifications in 2-2.

## **5. REMARK**

### **5.1 Static voltage**

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

### **5.2 Ultrasonic cleaning**

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

### **5.3 Soldering**

Only leads of component may be soldered. Please avoid soldering another part of component.